



PMV50EPEA

30 V, P-channel Trench MOSFET

30 June 2016

Product data sheet

1. General description

P-channel enhancement mode Field-Effect Transistor (FET) in a small SOT23 (TO-236AB) Surface-Mounted Device (SMD) plastic package using Trench MOSFET technology.

2. Features and benefits

- Logic level compatible
- Very fast switching
- Trench MOSFET technology
- ElectroStatic Discharge (ESD) protection > 2 kV HBM
- AEC-Q101 qualified

3. Applications

- Relay driver
- High-speed line driver
- High-side loadswitch
- Switching circuits

4. Quick reference data

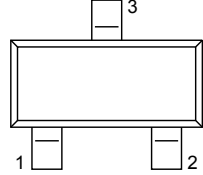
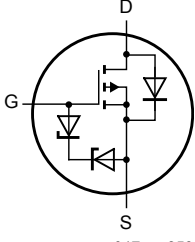
Table 1. Quick reference data

| Symbol | Parameter | Conditions | Min | Typ | Max | Unit |
|-------------------------------|----------------------------------|--|-----|-----|------|------|
| V_{DS} | drain-source voltage | $T_j = 25\text{ °C}$ | - | - | -30 | V |
| V_{GS} | gate-source voltage | | -20 | - | 20 | V |
| I_D | drain current | $V_{GS} = -10\text{ V}; T_{amb} = 25\text{ °C}$ | [1] | - | -4.2 | A |
| Static characteristics | | | | | | |
| $R_{DS(on)}$ | drain-source on-state resistance | $V_{GS} = -10\text{ V}; I_D = -4.2\text{ A}; T_j = 25\text{ °C}$ | - | 35 | 45 | mΩ |

[1] Device mounted on an FR4 Printed-Circuit Board (PCB), single-sided copper, tin-plated, mounting pad for drain 6 cm².

5. Pinning information

Table 2. Pinning information

| Pin | Symbol | Description | Simplified outline | Graphic symbol |
|-----|--------|-------------|---|--|
| 1 | G | gate |  <p>TO-236AB (SOT23)</p> |  <p>017aaa259</p> |
| 2 | S | source | | |
| 3 | D | drain | | |

6. Ordering information

Table 3. Ordering information

| Type number | Package | | |
|-------------|----------|--|---------|
| | Name | Description | Version |
| PMV50EPEA | TO-236AB | plastic surface-mounted package; 3 leads | SOT23 |

7. Marking

Table 4. Marking codes

| Type number | Marking code |
|-------------|--------------|
| PMV50EPEA | DQ% [1] |

[1] % = placeholder for manufacturing site code

8. Limiting values

Table 5. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

| Symbol | Parameter | Conditions | | Min | Max | Unit |
|---------------------------|--|--|-----|-----|-------|------|
| V_{DS} | drain-source voltage | $T_j = 25\text{ °C}$ | | - | -30 | V |
| V_{GS} | gate-source voltage | | | -20 | 20 | V |
| I_D | drain current | $V_{GS} = -10\text{ V}; T_{amb} = 25\text{ °C}$ | [1] | - | -4.2 | A |
| | | $V_{GS} = -10\text{ V}; T_{amb} = 100\text{ °C}$ | [1] | - | -2.7 | A |
| I_{DM} | peak drain current | $T_{amb} = 25\text{ °C};$ single pulse; $t_p \leq 10\text{ }\mu\text{s}$ | | - | -16.9 | A |
| $E_{DS(AL)S}$ | non-repetitive drain-source avalanche energy | $T_{j(\text{init})} = 25\text{ °C}; I_D = -1.3\text{ A};$ DUT in avalanche (unclamped) | | - | 19.5 | mJ |
| P_{tot} | total power dissipation | $T_{amb} = 25\text{ °C}$ | [2] | - | 480 | mW |
| | | | [1] | - | 1.2 | W |
| | | $T_{sp} = 25\text{ °C}$ | | - | 6.95 | W |
| T_j | junction temperature | | | -55 | 150 | °C |
| T_{amb} | ambient temperature | | | -55 | 150 | °C |
| T_{stg} | storage temperature | | | -65 | 150 | °C |
| Source-drain diode | | | | | | |
| I_S | source current | $T_{amb} = 25\text{ °C}$ | [1] | - | -4 | A |
| ESD maximum rating | | | | | | |
| V_{ESD} | electrostatic discharge voltage | HBM | [3] | - | 2000 | V |

[1] Device mounted on an FR4 Printed-Circuit Board (PCB), single-sided copper, tin-plated, mounting pad for drain 6 cm^2 .

[2] Device mounted on an FR4 PCB, single-sided copper, tin-plated and standard footprint.

[3] Measured between all pins.



Fig. 1. Normalized total power dissipation as a function of junction temperature

$$P_{der} = \frac{P_{tot}}{P_{tot(25^\circ\text{C})}} \times 100 \%$$



Fig. 2. Normalized continuous drain current as a function of junction temperature

$$I_{der} = \frac{I_D}{I_{D(25^\circ\text{C})}} \times 100 \%$$

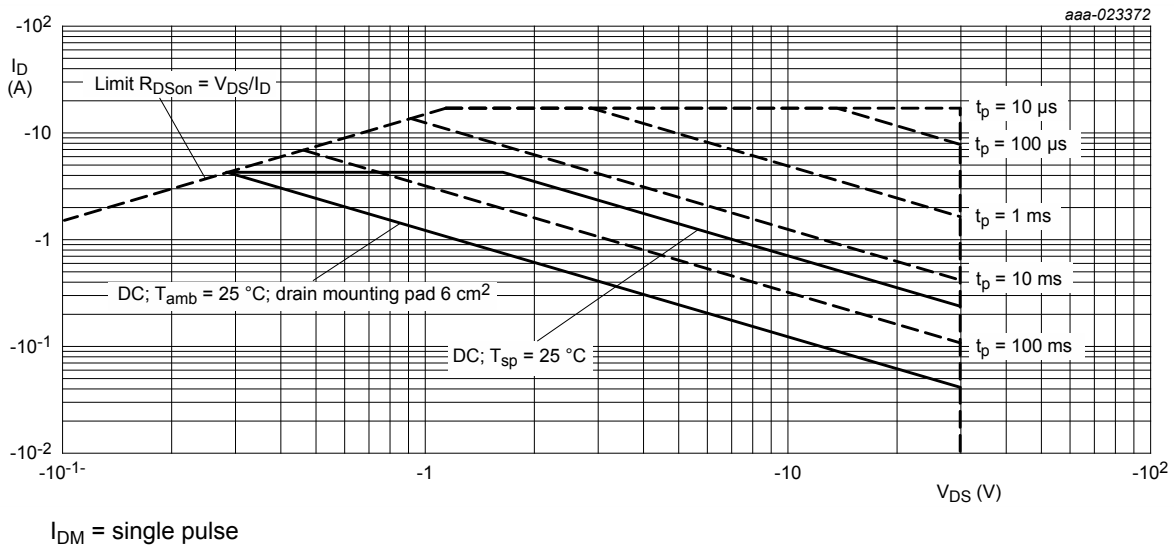


Fig. 3. Safe operating area; junction to ambient; continuous and peak drain currents as a function of drain-source voltage

9. Thermal characteristics

Table 6. Thermal characteristics

| Symbol | Parameter | Conditions | | Min | Typ | Max | Unit |
|----------------------|---|-------------|-----|-----|-----|-----|------|
| R _{th(j-a)} | thermal resistance from junction to ambient | in free air | [1] | - | 227 | 261 | K/W |
| | | | [2] | - | 91 | 104 | K/W |

| Symbol | Parameter | Conditions | Min | Typ | Max | Unit |
|----------------|--|------------|-----|-----|-----|------|
| $R_{th(j-sp)}$ | thermal resistance from junction to solder point | | - | 13 | 18 | K/W |

- [1] Device mounted on an FR4 PCB, single-sided copper, tin-plated and standard footprint.
- [2] Device mounted on an FR4 PCB, single-sided copper, tin-plated, mounting pad for drain 6 cm².

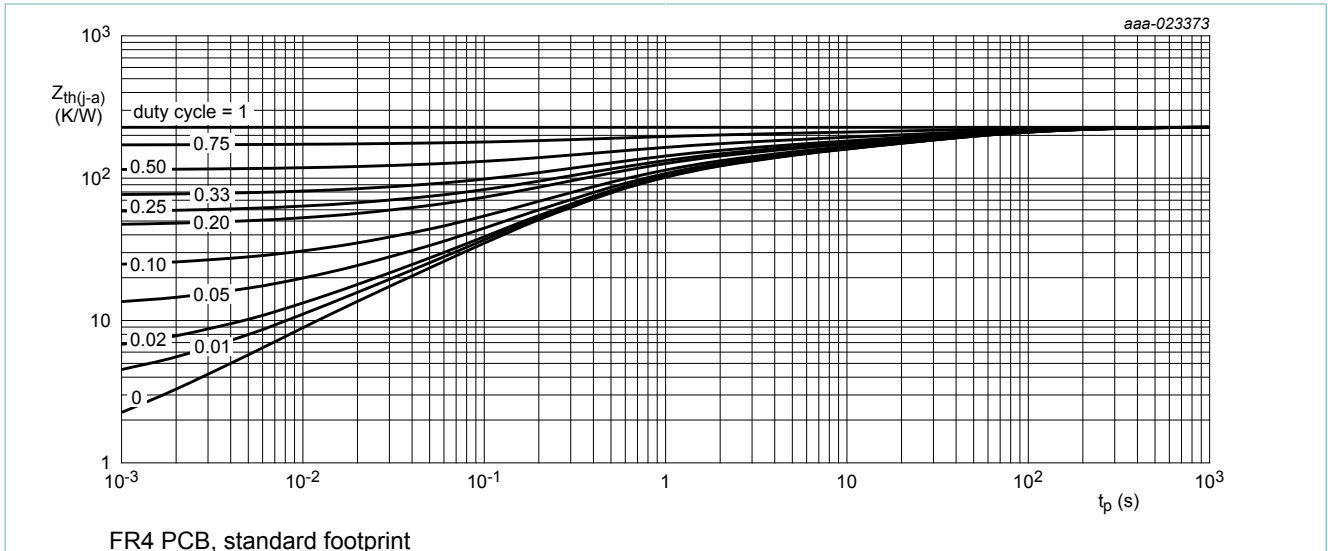


Fig. 4. Transient thermal impedance from junction to ambient as a function of pulse duration; typical values

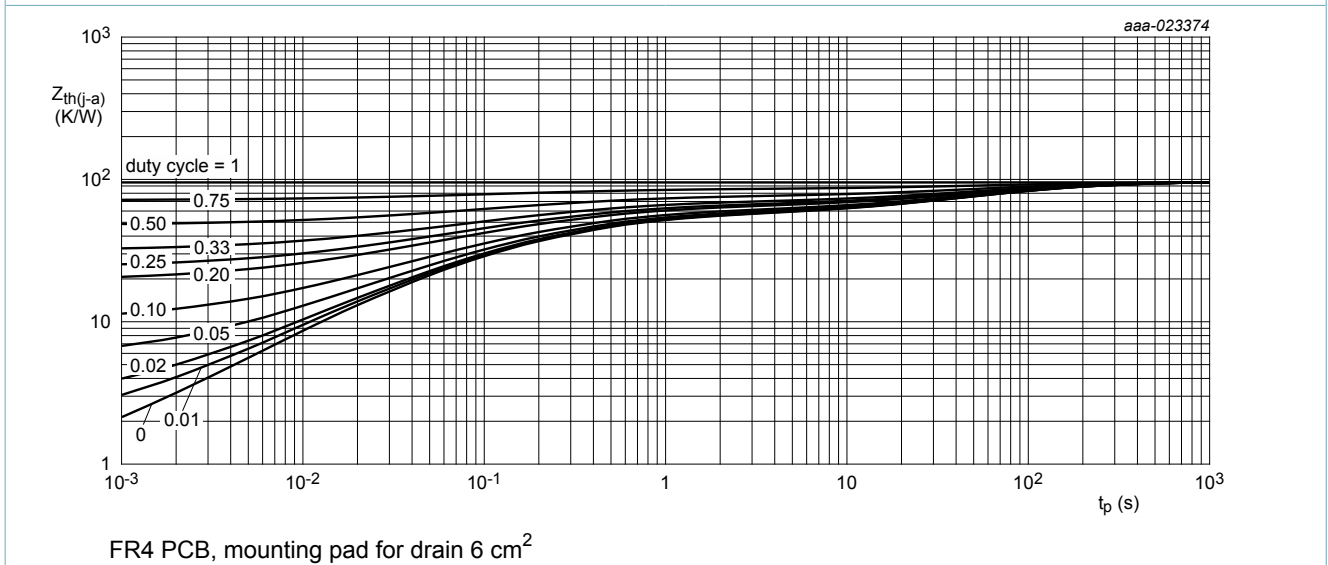


Fig. 5. Transient thermal impedance from junction to ambient as a function of pulse duration; typical values

10. Characteristics

Table 7. Characteristics

| Symbol | Parameter | Conditions | Min | Typ | Max | Unit |
|--------------------------------|----------------------------------|---|--|-------|------|---------------|
| Static characteristics | | | | | | |
| $V_{(BR)DSS}$ | drain-source breakdown voltage | $I_D = -250 \mu\text{A}$; $V_{GS} = 0 \text{ V}$; $T_j = 25 \text{ }^\circ\text{C}$ | -30 | - | - | V |
| V_{GSth} | gate-source threshold voltage | $I_D = -250 \mu\text{A}$; $V_{DS} = V_{GS}$; $T_j = 25 \text{ }^\circ\text{C}$ | -1 | -2 | -3 | V |
| I_{DSS} | drain leakage current | $V_{DS} = -30 \text{ V}$; $V_{GS} = 0 \text{ V}$; $T_j = 25 \text{ }^\circ\text{C}$ | - | - | -1 | μA |
| I_{GSS} | gate leakage current | $V_{GS} = 20 \text{ V}$; $V_{DS} = 0 \text{ V}$; $T_j = 25 \text{ }^\circ\text{C}$ | - | - | 10 | μA |
| | | $V_{GS} = -20 \text{ V}$; $V_{DS} = 0 \text{ V}$; $T_j = 25 \text{ }^\circ\text{C}$ | - | - | -10 | μA |
| | | $V_{GS} = 10 \text{ V}$; $V_{DS} = 0 \text{ V}$; $T_j = 25 \text{ }^\circ\text{C}$ | - | - | 2 | μA |
| | | $V_{GS} = -10 \text{ V}$; $V_{DS} = 0 \text{ V}$; $T_j = 25 \text{ }^\circ\text{C}$ | - | - | -2 | μA |
| R_{DSon} | drain-source on-state resistance | $V_{GS} = -10 \text{ V}$; $I_D = -4.2 \text{ A}$; $T_j = 25 \text{ }^\circ\text{C}$ | - | 35 | 45 | m Ω |
| | | $V_{GS} = -10 \text{ V}$; $I_D = -4.2 \text{ A}$; $T_j = 150 \text{ }^\circ\text{C}$ | - | 51 | 67 | m Ω |
| | | $V_{GS} = -4.5 \text{ V}$; $I_D = -3.3 \text{ A}$; $T_j = 25 \text{ }^\circ\text{C}$ | - | 49 | 72 | m Ω |
| g_{fs} | forward transconductance | $V_{DS} = -10 \text{ V}$; $I_D = -4.2 \text{ A}$; $T_j = 25 \text{ }^\circ\text{C}$ | - | 13.5 | - | S |
| R_G | gate resistance | $f = 1 \text{ MHz}$ | - | 13 | - | Ω |
| Dynamic characteristics | | | | | | |
| $Q_{G(tot)}$ | total gate charge | $V_{DS} = -15 \text{ V}$; $I_D = -4.2 \text{ A}$; $V_{GS} = -10 \text{ V}$; $T_j = 25 \text{ }^\circ\text{C}$ | - | 12.8 | 19.2 | nC |
| Q_{GS} | gate-source charge | | - | 2.2 | - | nC |
| Q_{GD} | gate-drain charge | | - | 2.2 | - | nC |
| C_{iss} | input capacitance | $V_{DS} = -15 \text{ V}$; $f = 1 \text{ MHz}$; $V_{GS} = 0 \text{ V}$; $T_j = 25 \text{ }^\circ\text{C}$ | - | 793 | - | pF |
| C_{oss} | output capacitance | | - | 134 | - | pF |
| C_{riss} | reverse transfer capacitance | | - | 84 | - | pF |
| $t_{d(on)}$ | turn-on delay time | | $V_{DS} = -15 \text{ V}$; $I_D = -4.2 \text{ A}$; $V_{GS} = -10 \text{ V}$; $R_{G(ext)} = 6 \text{ } \Omega$; $T_j = 25 \text{ }^\circ\text{C}$ | - | 6 | - |
| t_r | rise time | - | | 19 | - | ns |
| $t_{d(off)}$ | turn-off delay time | - | | 36 | - | ns |
| t_f | fall time | - | | 19 | - | ns |
| Source-drain diode | | | | | | |
| V_{SD} | source-drain voltage | $I_S = -4 \text{ A}$; $V_{GS} = 0 \text{ V}$; $T_j = 25 \text{ }^\circ\text{C}$ | - | -0.75 | -1.2 | V |

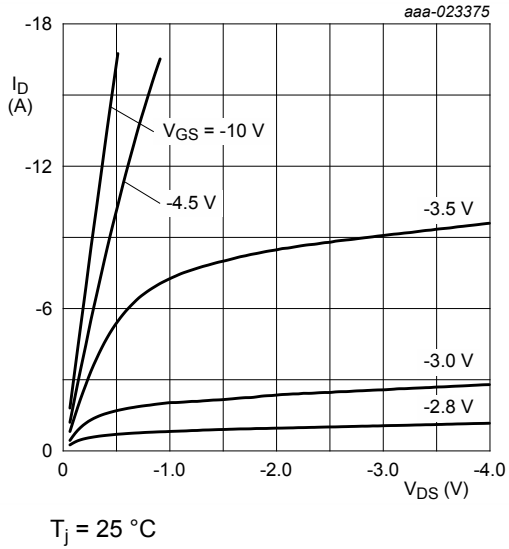


Fig. 6. Output characteristics: drain current as a function of drain-source voltage; typical values

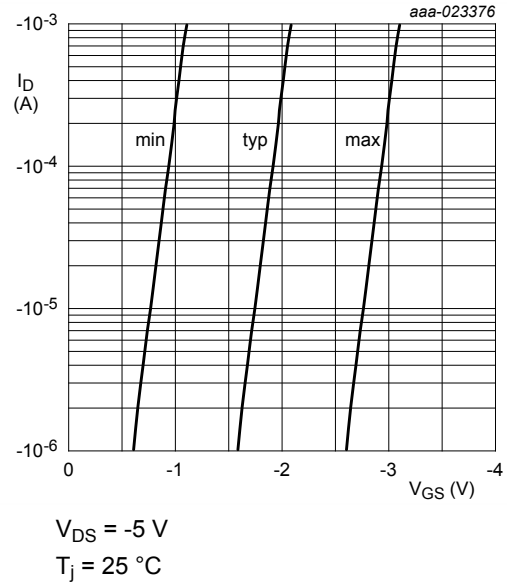


Fig. 7. Sub-threshold drain current as a function of gate-source voltage

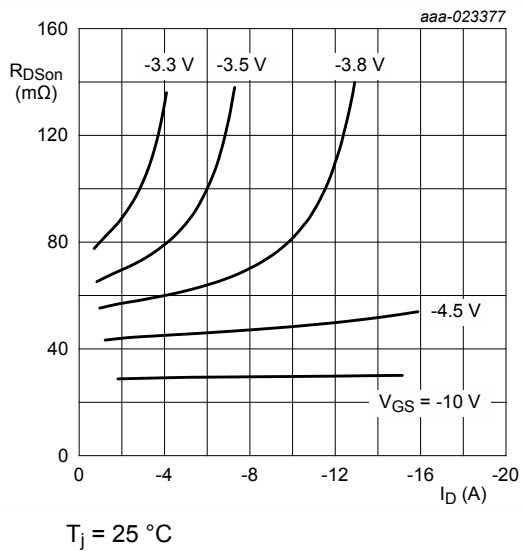


Fig. 8. Drain-source on-state resistance as a function of drain current; typical values

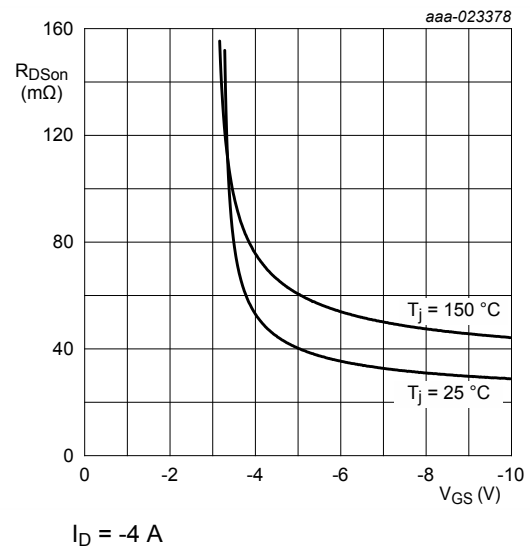


Fig. 9. Drain-source on-state resistance as a function of gate-source voltage; typical values

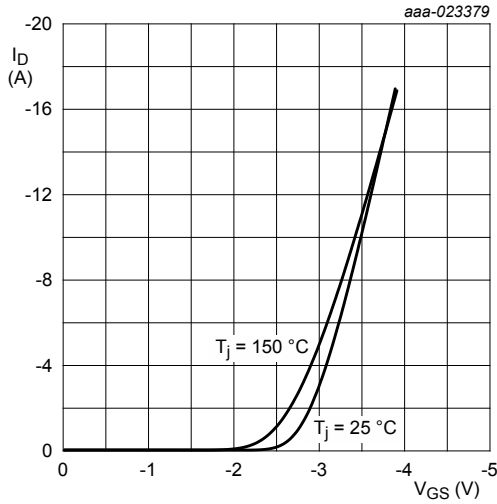


Fig. 10. Transfer characteristics: drain current as a function of gate-source voltage; typical values

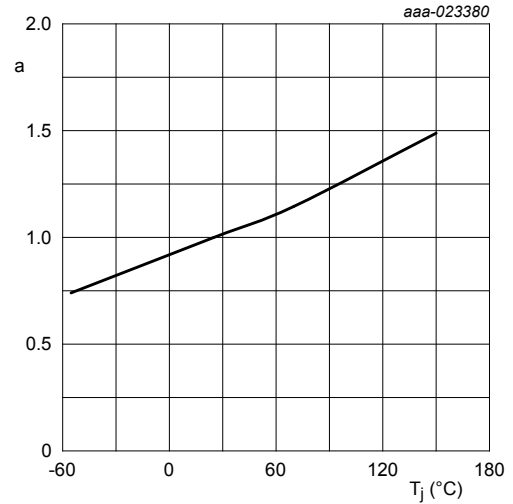


Fig. 11. Normalized drain-source on-state resistance as a function of junction temperature; typical values

$$a = \frac{R_{DSon}}{R_{DSon(25\text{ }^{\circ}\text{C})}}$$

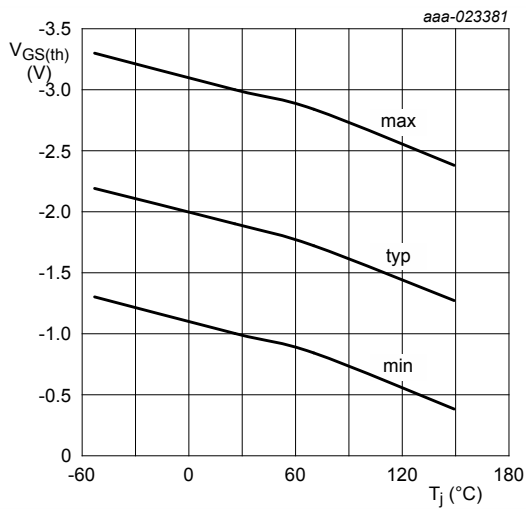


Fig. 12. Gate-source threshold voltage as a function of junction temperature

$I_D = -250\ \mu\text{A}; V_{DS} = V_{GS}$

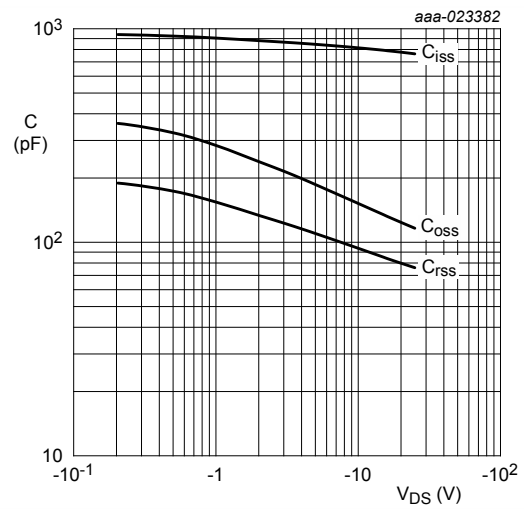
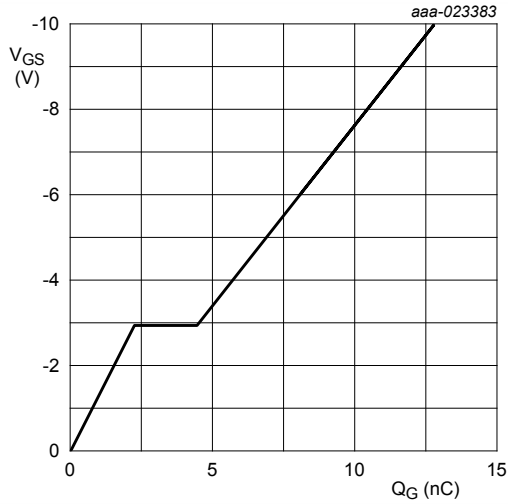


Fig. 13. Input, output and reverse transfer capacitances as a function of drain-source voltage; typical values

$f = 1\ \text{MHz}; V_{GS} = 0\ \text{V}$



$V_{DS} = -15 \text{ V}; I_D = -4 \text{ A}$

Fig. 14. Gate-source voltage as a function of gate charge; typical values

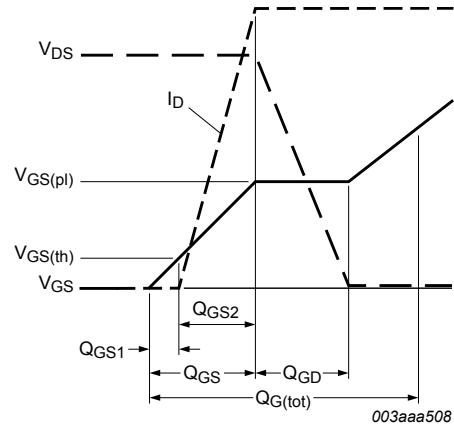
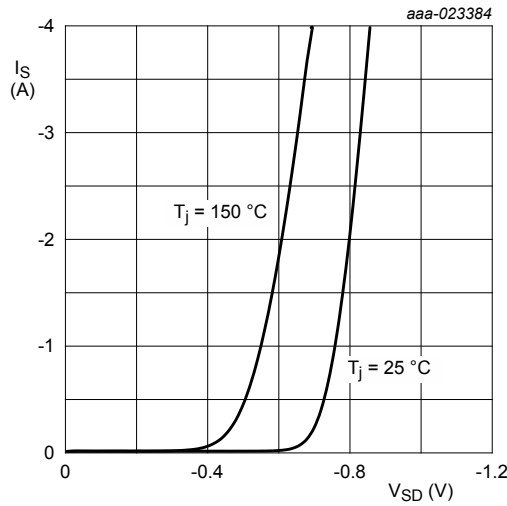


Fig. 15. Gate charge waveform definitions



$V_{GS} = 0 \text{ V}$

Fig. 16. Source current as a function of source-drain voltage; typical values

11. Test information



Fig. 17. Duty cycle definition

11.1 Quality information

This product has been qualified in accordance with the Automotive Electronics Council (AEC) standard Q101 - Stress test qualification for discrete semiconductors, and is suitable for use in automotive applications.

12. Package outline

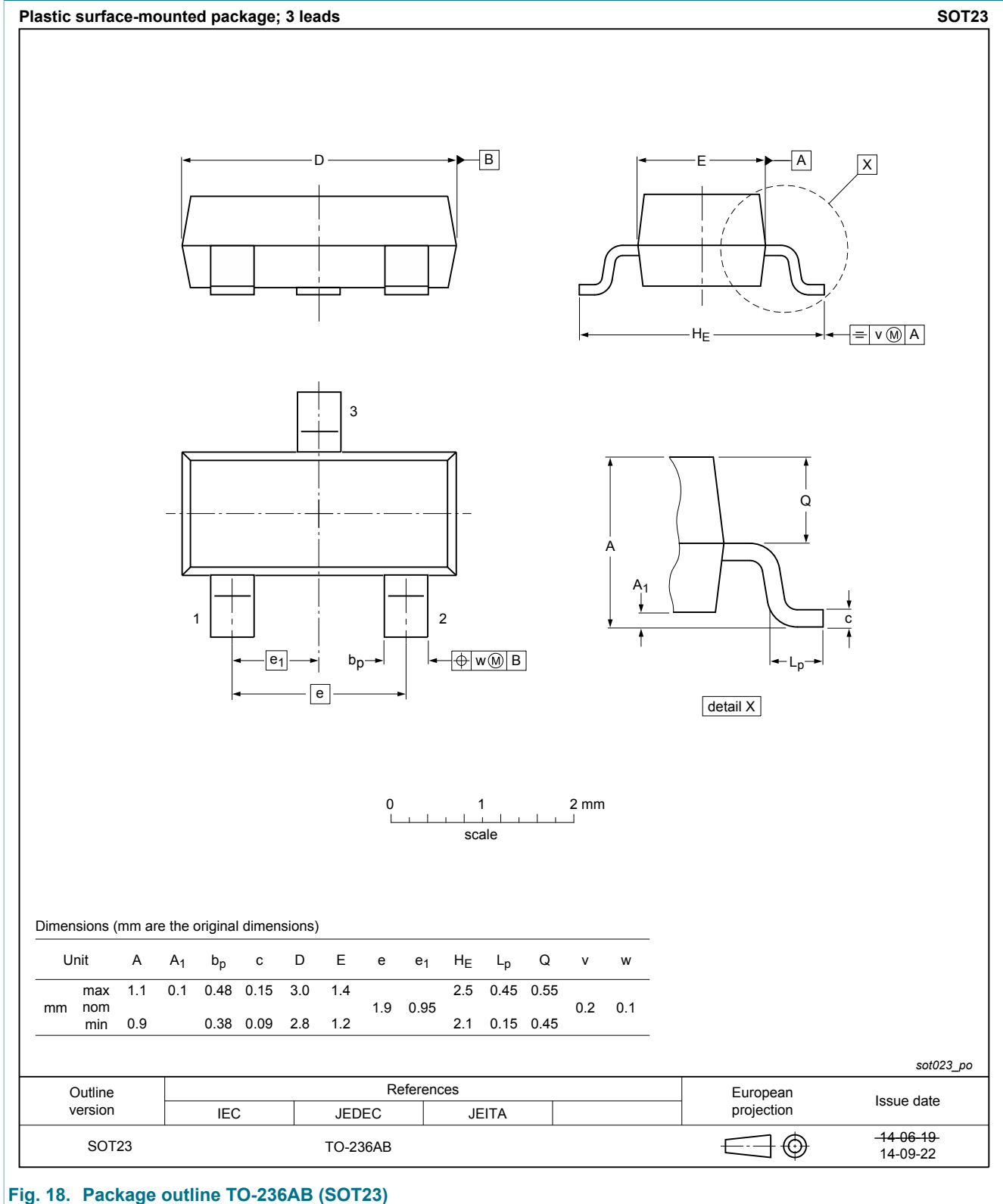


Fig. 18. Package outline TO-236AB (SOT23)

13. Soldering



Fig. 19. Reflow soldering footprint for TO-236AB (SOT23)



Fig. 20. Wave soldering footprint for TO-236AB (SOT23)

14. Revision history

Table 8. Revision history

| Data sheet ID | Release date | Data sheet status | Change notice | Supersedes |
|---------------|--------------|--------------------|---------------|------------|
| PMV50EPEA v.1 | 20160630 | Product data sheet | - | - |

15. Legal information

15.1 Data sheet status

| Document status [1][2] | Product status [3] | Definition |
|--------------------------------|--------------------|---|
| Objective [short] data sheet | Development | This document contains data from the objective specification for product development. |
| Preliminary [short] data sheet | Qualification | This document contains data from the preliminary specification. |
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- [2] The term 'short data sheet' is explained in section "Definitions".
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